## AMENDMENTS TO THE CLAIMS

- 2. (Original) An aluminum nitride junction body according to claim 1, wherein the area ratio of the sintered metal layer on the junction surface is in a range of 50 to 90%.
- 3. (Withdrawn) A method of producing an aluminum nitride junction body comprising the steps of:

providing two pieces of aluminum nitride sintered plates;

forming a recessed portion in a surface of one aluminum nitride sintered plate;

charging an electrically conducting paste containing, as a conductor component, a tungsten powder or a molybdenum powder having an average particle size ( $D_{50}$ ) of not larger than 3.5  $\mu$ m into the recessed portion;

forming an adhesive layer by applying an adhesive paste containing aluminum nitride as an adhesive component onto a whole surface of the aluminum nitride sintered plate charged with the electrically conducting paste; dewaxing the electrically conducting paste and the adhesive paste;

effecting a primary sintering while contacting the other aluminum nitride sintered plate onto the surface where the adhesive layer is formed of the aluminum nitride sintered plate with a pressure of 0.5 to 10 MPa at a temperature of 1600 to 1700°C for 0.5 to 4 hours; and

effecting a secondary sintering at a temperature of 1800 to 1900°C for 2 to 8 hours following the primary sintering.

4. (Withdrawn) A method of producing an aluminum nitride junction body according to claim 3, wherein the electrically conducting paste is charged into the recessed portion in an amount, calculated as a solid component, of 1.05 to 1.5 times as great as the volume of the recessed portion.